



CALL FOR PAPERS

12th IEEE WORKSHOP ON

SIGNAL PROPAGATION ON INTERCONNECTS

Pending Sponsorship by the IEEE Computer Society – Test Technology Technical Council (TTTC)
and by the IEEE Components, Packaging, and Manufacturing Technology (CPMT) Society

First time in France!

May 12-15, 2008 - "Pope's Palace", Avignon, France
<http://spi.univ-brest.fr>

During the last ten years, the IEEE Workshop on Signal Propagation on Interconnects has been developed into a forum of exchange on the latest research and developments in the field of interconnect modeling, simulation and measurement at chip, board, and package level. The event is also meant to bring together developers and researchers from industry and academia in order to encourage cooperation. In view of the last years success the committee is looking forward to the 12th IEEE Workshop on Signal Propagation on Interconnects where world class developers and researchers will share and discuss leading edge results in Avignon, France. The workshop will be held in English. Detailed information about the workshop and its location are available on the website spi.univ-brest.fr. The committee is looking forward to your participation.



Main topics of the workshop will include, but are not limited to:

- Frequency Domain Measurement Techniques
- Time Domain Measurement Techniques
- Modeling Techniques of Package % On-Chip Interconnects
- Macro-Modeling
- Simulation Techniques for Interconnect Structures
- Electromagnetic Field Theory
- Analysis and Modeling of Power Distribution Networks
- Propagation Characteristics on Transmission Lines
- RF and Microwave Interconnects
- Coupling Effects on Interconnects
- Substrate Effects
- Guided Waves on Interconnects
- Radiation & Interference
- Electromagnetic Compatibility
- Power/Ground-Noise
- Testing & Interconnects
- Optical Interconnects
- Wireless Interconnects

Visit :
spi.univ-brest.fr

Submission of abstracts:

Those who wish to contribute to the workshop should send (by e-mail only) a formatted two-page or four-page paper to the Program Chair by **February 8, 2008** (please see the submission instruction on our website <http://spi.univ-brest.fr>). If the paper is accepted, it will be reproduced, as is, in the workshop proceedings. Notification about acceptance will be given by March 15, 2008.

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